



International Conference on Powder and Powder Metallurgy, 2023, Kyoto

Date: Oct. 16 (Mon) - Oct. 18 (Wed), 2023 Venue: Doshisha University, Kambaikan

1st Announcement (Restart) JSPMIC2023

Organized by Japan Society of Powder and Powder Metallurgy (JSPM)

DATE : October 16 (Mon)~ October 18 (Wed), 2023

VENUE : Doshisha University, Kambaikan, Kyoto, Japan



Submission Deadline of Application Form for the Presentation: **30th June (Fri), 2023, 24:00 <JST>**

Technical Program

Technical sessions (for oral and poster presentations) listed below are scheduled. The official language of the conference will be English. Poster Awards will be awarded to outstanding poster presentations.

Submission Application Form for the Presentation

Participants wishing to make a presentation in the technical program are cordially invited to **submit a short abstract for the program committee** in English **not later than 30 June (Fri), 2023, 24:00 <JST>**

Submission URL <https://jspmic.confit.atlas.jp/login>

All submitted papers will be reviewed and allocated to Oral or Poster Sessions by the Program Committee, based on the authors' choices. The notification of acceptance will be delivered to authors by e-mail by the beginning of August 2023.

Technical Session Categories

A-1: Synthesis, Modification and Properties of Functional Particle

A-2: Powder Handling and Processing

A-3: Colloidal Dispersion and Processing

B-1: Powder Compaction

B-2: Powder Forging, Rolling, Extrusion

B-3: Spray Forming

B-4: CIP and HIP

B-5: PIM (Powder Injection Molding)

B-6: Additive Manufacturing with Powder Metallurgy

C-1: Sintering and Post Processing

C-2: Spark Plasma Sintering and Field/Current Assisted Process

C-3: Testing and Evaluation

C-4: Quality and Environment Control

C-5: Powder Manufacturing and Treatment

C-6: Mechanical Alloying

C-7: Modeling and Simulation

D-1: Iron and Steel Materials

D-2: Non-ferrous Materials and High Entropy Alloys

D-3: Refractory and High Temperature Materials

D-4: Automotive Applications

D-5: Aerospace Applications

E-1: Cemented Carbide

E-2: Cermet

E-3: Diamond, CBN, Ceramics

E-4: Hard Coatings

F-1: Soft Magnetic Materials

F-2: Hard Magnetic Materials

F-3: Materials and Devices with Magnetic Functionality

G-1: Composite and Hybrid Materials

G-2: Porous and Cellular Materials

G-3: Friction Materials

G-4: Metallic glasses (Bulk, Rapidly quenched)

G-5: Nano and Ultra-fine Materials

G-6: Optical Materials

G-7: Functionally Graded and Layered Materials

G-8: Bio-Medical Materials

G-9: Ionic Conducting Materials

G-10: Battery and Electrode

G-11: Magnetic, Superconducting, Electric, Dielectric and Thermoelectric Materials

G-12: Electronic Components and Packaging Materials

G-13: Power Electronic Devices

Abstract Submission

Submission Deadline of Abstract: September 13 (Wed) 24:00 <JST>

All presenters should submit abstract by using the Word file of “template JSPMIC2023” and converting it into pdf file. You will upload the pdf file through the following URL using your ID and password when you created your account.

<https://jspmfuncyio.confit.atlas.jp/login>

The abstract of the JSPMIC2023 will be released only on its web site on October 2nd (Mon), 2023, (2 weeks before the Conference). The authors must complete the procedures related to patents by the release date if necessary.

For making the abstract, you should

1. Use the template (a word file: A4 size (210mm×297mm), one sheet) that you can download from JSPMIC2023 website.
2. Please confirm the details, for instance, font, figures, how to embedding the fonts on the website.
3. Convert Word file to PDF file (Size of PDF file is up to 5MB).
4. Upload your abstract by **September 13th (Wed), 24:00 <JST>, 2023**.
5. Please be sure to use the program number (example:13A-A1-01) that we are informing for the file name.
6. We do not give you proofreading. Please submit a complete document by the author’s responsibility.

JSPMIC2023 Paper Award

The committee of JSPMIC2023 and the editorial board of the journal of JSPM have decided to **establish “JSPMIC2023 Paper Award”**. The items for the award are as below;

1. The content of the paper is the same as the presentation at JSPMIC2023.
2. The submission of the paper is the same as a paper in the category (2.1.1) of the journal of JSPM below.

[Guideline for Submission. pdf](#)

3. The period of submission is **from October 19th 2023 to February 29th 2024**.
4. The language is English.
5. The review (judgement) of the paper after the submission is also the same as a paper in the category (2.1.1) of the journal of JSPM (JJSPM).

Registration

Registration will be available through this web-site from the end of August.

Registration Fees

Early-bird (Due: September 22, 2023) Regular: 50,000 JPY Student: 10,000 JPY

Late/On-Site Regular: 60,000 JPY Student: 12,000 JPY

Accompanying person 10,000 JPY

- Regular registration includes attendance at all Technical Sessions, and Conference party.
- Student registration includes attendance at all Technical Sessions.
- All participants are able to attend at the Autumn Meeting of JSPM, 2023 for free.
- Accompanying person registration includes attendance at the Conference party.
- All participants are advised to pre-register to ensure admission to the conference.

Important Dates

Application Form for the Presentation:

30th June (Fri), 2023

Abstract Submission:

13th September (Wed), 2023

Early-bird Registration:

22nd September (Wed), 2023

For any inquiries, please contact:

Secretariat of JSPMIC2023

jspmic2022@jspm.or.jp

<The email address remains the same as 2022's>

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